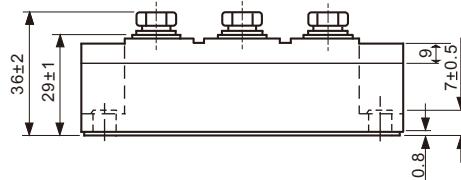
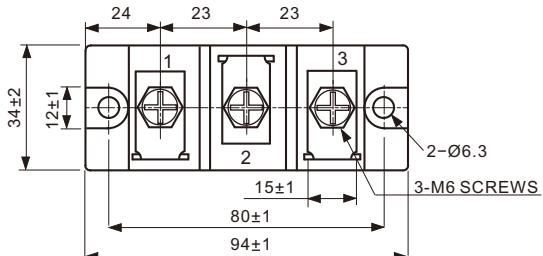


### Standard Recovery Diodes, 200 A (INT-A-PAK Power Modules)



#### FEATURES

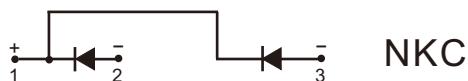
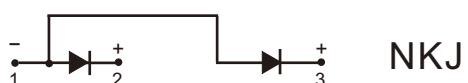
- High voltage
- Electrically isolated by DBC ceramic ( $\text{Al}_2\text{O}_3$ )
- 3000 V<sub>RMS</sub> isolating voltage
- Industrial standard package
- High surge capability
- Modules uses high voltage power diodes in four basic configurations
- Simple mounting
- UL approved file E320098
- Compliant to RoHS
- Designed and qualified for multiple level


**RoHS**  
COMPLIANT


All dimensions in millimeters

#### APPLICATIONS

- DC motor control and drives
- Battery charges
- Welders
- Power converters



PRODUCT SUMMARY	
I <sub>F(AV)</sub>	200 A
Type	Modules - Diode, High Voltage

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUE	UNITS
I <sub>F(AV)</sub>		200	A
	T <sub>C</sub>	100	°C
I <sub>F(RMS)</sub>		314	A
	50 Hz	8000	
I <sub>FSM</sub>	60 Hz	8376	
	50 Hz	320	kA <sup>2</sup> s
I <sup>2</sup> t	60 Hz	291	
		3200	kA <sup>2</sup> /s
I <sup>2</sup> √t		400 to 1600	V
V <sub>RRM</sub>		-40 to 150	°C
T <sub>J</sub>	Range		

**ELECTRICAL SPECIFICATIONS**

<b>VOLTAGE RATINGS</b>				
<b>TYPE NUMBER</b>	<b>VOLTAGE CODE</b>	<b><math>V_{RRM}</math>, MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V</b>	<b><math>V_{RSM}</math>, MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V</b>	<b><math>I_{RRM}</math> AT 150 °C mA</b>
NKD200 NKJ200 NKC200	04	400	500	10
	08	800	900	
	12	1200	1300	
	14	1400	1500	
	16	1600	1700	

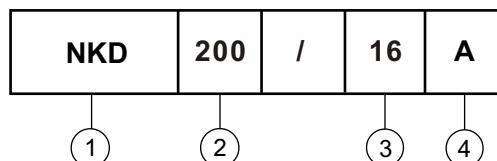
<b>FORWARD CONDUCTION</b>									
<b>PARAMETER</b>	<b>SYMBOL</b>	<b>TEST CONDITIONS</b>			<b>VALUE</b>	<b>UNITS</b>			
Maximum average on-state current at case temperature	$I_{F(AV)}$	180° conduction, half sine wave			200	A			
					100	°C			
Maximum RMS on-state current	$I_{F(RMS)}$	180° conduction, half sine wave ,50Hz , $T_C = 100^\circ C$			314	A			
Maximum peak, one-cycle, on-state non-repetitive surge current	$I_{FSM}$	$t = 10 \text{ ms}$	No voltage reapplied		8000				
		$t = 8.3 \text{ ms}$			8376				
		$t = 10 \text{ ms}$	100% $V_{RRM}$ reapplied		6720				
		$t = 8.3 \text{ ms}$			7036				
Maximum $I^2t$ for fusing	$I^2t$	$t = 10 \text{ ms}$	No voltage reapplied	Sine half wave, initial $T_J = T_J$ maximum	320	kA <sup>2</sup> s			
		$t = 8.3 \text{ ms}$			291				
		$t = 10 \text{ ms}$	100% $V_{RRM}$ reapplied		226				
		$t = 8.3 \text{ ms}$			205				
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1 \text{ ms to } 10 \text{ ms}$ , no voltage reapplied			3200	kA <sup>2</sup> $\sqrt{s}$			
Maximum forward voltage drop	$V_{FM}$	$I_{FM} = 600A$ , $T_J = 25^\circ C$ , 180° conduction			1.4	V			

<b>BLOCKING</b>					
<b>PARAMETER</b>	<b>SYMBOL</b>	<b>TEST CONDITIONS</b>		<b>VALUES</b>	<b>UNITS</b>
Maximum peak reverse and off-state leakage current	$I_{RRM}$	$T_J = 150^\circ C$		10	mA
RMS isolation Voltage	$V_{ISO}$	50 Hz, circuit to base ,all terminals shorted , $t = 1s$		3000	V
		$t = 60s$		2500	

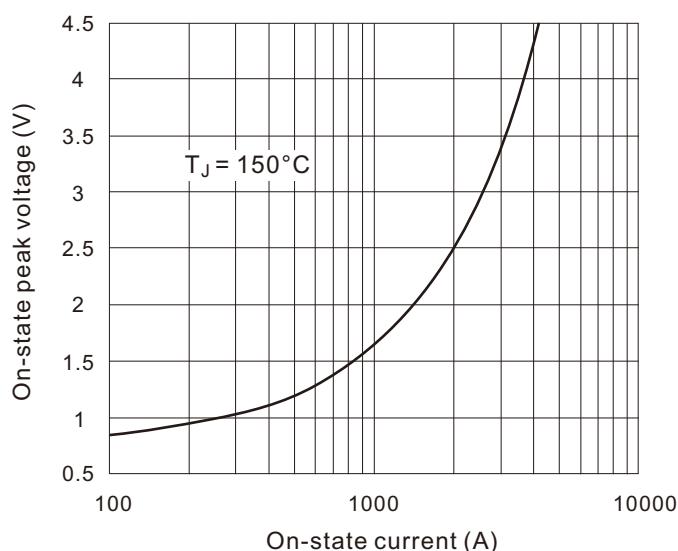
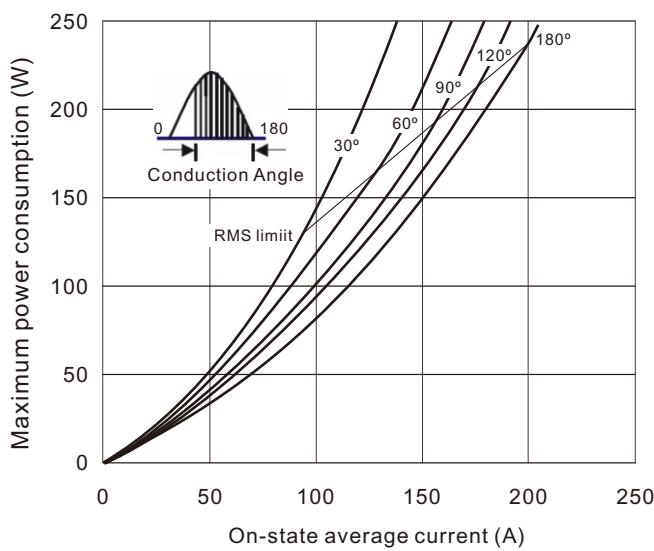
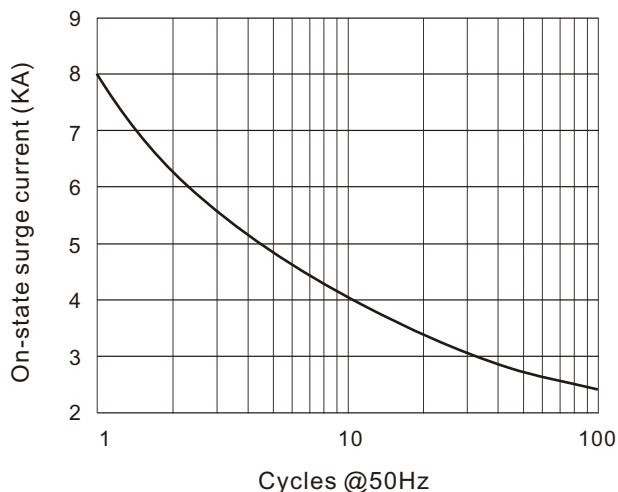
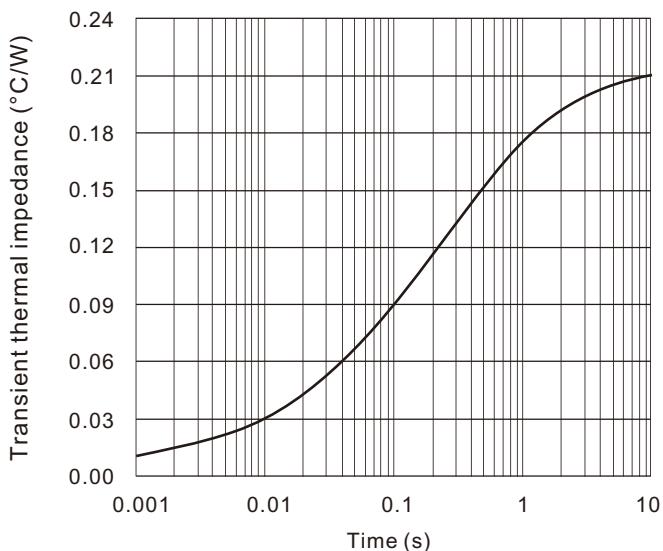
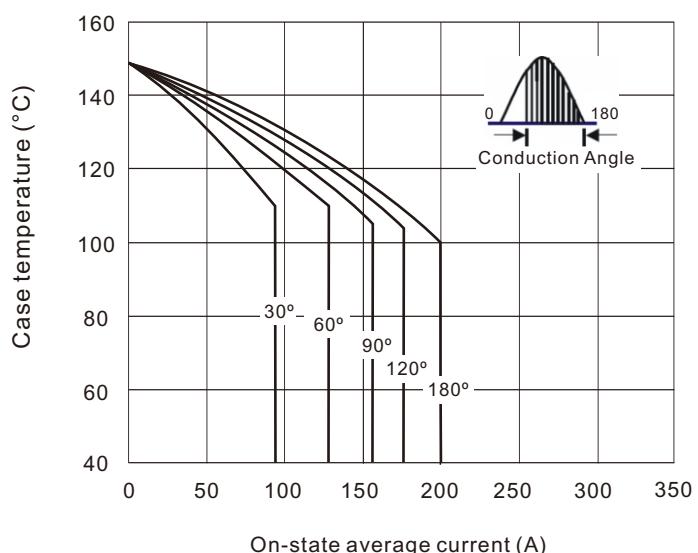
THERMAL AND MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction operating temperature range	$T_{Stg}, T_J$		- 40 to 150	°C
Maximum thermal resistance, junction to case per junction	$R_{thJC}$	DC operation	0.21	°C/W
Maximum thermal resistance, case to heatsink per module	$R_{thCS}$	Mounting surface, smooth, flat and greased	0.075	
Mounting torque ± 10 % IAP to heatsink, M6 busbar to IAP, M6		A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound. Lubricated threads.	4 to 6	N.m
Approximate weight				220 g
				7.8 oz.
Case style				New INT-A-PAK

### ORDERING INFORMATION TABLE

Device code



- [1] - Module type: NKD, NKJ and NKC for (Diode + Diode) module
- [2] - Current rating:  $I_F(AV)$
- [3] - Voltage code x 100 =  $V_{RRM}$
- [4] - Assembly type, "A" for soldering type

**Nell High Power Products**
**Fig.1 On-state current vs. voltage characteristic**

**Fig.3 Power consumption vs. average current**

**Fig.5 On-state surge current vs. cycles**

**Fig.2 Transient thermal impedance(junction-case)**

**Fig.4 Case temperature vs. on-state average current**

**Fig.6  $I^2t$  Characteristic**
